

Appl. No. 09/980,225
Amdt. Dated July 14, 2003
Reply to Office Action of March 27, 2003

Amendments to the Claims:

This listing will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (previously amended): A molding material for use with carbon dioxide refrigerant, which comprises chlorinated polyethylene having a chloride content of 25-47% by weight.

Claim 2 (previously amended): A molding material for use with carbon dioxide refrigerant according to claim 1, wherein the chlorinated polyethylene is used as a blend with vinyl chloride-based resin.

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Claim 3 (previously amended): A molding material for use with carbon dioxide refrigerant according to claim 1, wherein an inorganic filler is further contained.

Claim 4 (previously amended): A molding material for use with carbon dioxide refrigerant according to claim 1, wherein a vinylic, epoxy or methacryloxy silane coupling agent is further contained.

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Claim 5 (previously amended): A molding material for use with carbon dioxide refrigerant according to claim 1, wherein 1-10 parts by weight of an organic peroxide is further contained on the basis of 100 parts by weight of the chlorinated polyethylene or its blend with the vinyl chloride-based resin.

Claim 6 (presently amended): A molding material for use with carbon dioxide refrigerant according to claim 1, ~~for use as a~~ wherein the molding material for is formed into a sealing materials element in ~~a carbon dioxide refrigerant-contacting apparatuses.~~ apparatus.

Claim 7 (previously amended): A molding material for use with carbon dioxide refrigerant according to claim 2, wherein a vinylic, epoxy or methacryloxy silane coupling agent is further contained.

Claim 8 (previously amended): A molding material for use with carbon dioxide refrigerant according to claim 2, wherein an inorganic filler is further contained.

Claim 9 (previously amended): A molding material for use with carbon dioxide refrigerant according to claim 2, wherein 1-10 parts by weight of an organic peroxide is further contained on the basis of 100 parts by weight of the chlorinated polyethylene or its blend with the vinyl chloride-based resin.

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Claim 10 (previously amended): A molding material for use with carbon dioxide refrigerant according to claim 4, wherein 1-10 parts by weight of an organic peroxide is further contained on the basis of 100 parts by weight of the chlorinated polyethylene or its blend with the vinyl chloride-based resin.

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Claim 11 (presently amended): A molding material for use with carbon dioxide refrigerant according to claim 2, ~~for use as a~~ wherein the molding material for is formed into a sealing materials element in a carbon dioxide refrigerant-contacting apparatuses. apparatus.

Claim 12 (presently amended): A molding material for use with carbon dioxide refrigerant according to claim 4, ~~for use as a~~ wherein the molding material for is formed into a sealing materials element in a carbon dioxide refrigerant-contacting apparatuses. apparatus.

Claim 13 (newly presented): In a carbon dioxide refrigerant system, a carbon dioxide sealing element made from a molding material which comprises chlorinated polyethylene having a chloride content of 25-47% by weight.

Claim 14 (newly presented): A carbon dioxide sealing element made from a molding material which comprises chlorinated polyethylene having a chloride content of 25-47% by weight.